

ABSTRACT

[Abstract]

The object of the present invention is to provide a mold release film that, during bonding of the CL film to the circuit exposure film, makes it possible to prevent that mold release layer bonds to the CL film and the circuit exposure film, and between the mold release layers, and to have better embeddability than the conventional PBT mold release layer. Mold release film 100 relating to the present invention is comprising mold release layer 110 that contains at least poly(butylene terephthalate) homopolymer (A), and a copolymer having a poly(butylene terephthalate) component (PBT) and a poly(tetramethylene glycol) component (PTMG).